

SEMICONDUCTOR APPARATUS AND
PROCESS OF PRODUCTION THEREOF

ABSTRACT OF THE DISCLOSURE

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10 A process of production of a semiconductor
apparatus which can suppress a rise in the electrical
resistance and a decline in the joint strength at the
bump connection interfaces and improve the connection
reliability when using the method of reinforcing the
bases of the bumps by a resin film. Bumps are formed on a
semiconductor wafer formed with a pattern circuit of a
semiconductor chip so as to connect to the circuit
15 pattern, a resin film is formed on the bump forming
surface of the semiconductor wafer to a thickness giving
a surface lower than the height of the bumps while
sealing the spaces between the bumps, plasma cleaning
etc., is used to remove the sealing resin components
20 deposited on the surface portions of the bumps or natural
oxides or other insulating impurities to clean and
activate the surfaces of the bumps, and the chip is
mounted on a mounting board.

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